

Abstract

The invention relates to a method and a device for the thermal treatment, especially short-term, of flat objects in particular, such as semi-conductor, glass or metal substrates. Heat is, at least in part, supplied to or taken away from both sides of said substrates by means of thermal conduction via a thermal conduction medium. The invention aims to improve the method and device so that they can be used effectively. To this end, a mixture consisting of two gases, differing greatly in their thermal conductivity, is used as a thermal conductive medium. The mixture on both sides of the substrate is individually adjusted so that the respective surface temperature is time-controlled by taking the respective heat exchange due to heat radiation into account.